

Hongkeun Park

List of Publications by Year in descending order

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#	ARTICLE	IF	CITATIONS
1	Initiated Chemical Vapor Deposition: A Versatile Tool for Various Device Applications. <i>Advanced Engineering Materials</i> , 2018, 20, 1700622.	3.5	93
2	Flexible, Low-Power Thin-Film Transistors Made of Vapor-Phase Synthesized High- k , Ultrathin Polymer Gate Dielectrics. <i>ACS Applied Materials & Interfaces</i> , 2017, 9, 20808-20817.	8.0	61
3	Highly stacked 3D organic integrated circuits with via-hole-less multilevel metal interconnects. <i>Nature Communications</i> , 2019, 10, 2424.	12.8	37
4	All-Solid-State Ion Synaptic Transistor for Wafer-Scale Integration with Electrolyte of a Nanoscale Thickness. <i>Advanced Functional Materials</i> , 2021, 31, 2010971.	14.9	34
5	Vertically stacked, low-voltage organic ternary logic circuits including nonvolatile floating-gate memory transistors. <i>Nature Communications</i> , 2022, 13, 2305.	12.8	23
6	A Single-Chamber System of Initiated Chemical Vapor Deposition and Atomic Layer Deposition for Fabrication of Organic/Inorganic Multilayer Films. <i>Advanced Engineering Materials</i> , 2017, 19, 1600819.	3.5	22
7	Systematic Control of Negative Transconductance in Organic Heterojunction Transistor for High-Performance, Low-Power Flexible Ternary Logic Circuits. <i>Small</i> , 2021, 17, e2103365.	10.0	20
8	Stretchable active matrix of oxide thin-film transistors with monolithic liquid metal interconnects. <i>Applied Physics Express</i> , 2018, 11, 126501.	2.4	17
9	Vapor-phase synthesis of sub-15 nm hybrid gate dielectrics for organic thin film transistors. <i>Journal of Materials Chemistry C</i> , 2017, 5, 4463-4470.	5.5	14
10	Graphene electrode with tunable charge transport in thin-film transistors. <i>Nano Research</i> , 2018, 11, 274-286.	10.4	14
11	Multi-Stage Organic Logic Circuits Using Via-Hole-Less Metal Interconnects. <i>IEEE Electron Device Letters</i> , 2020, 41, 1685-1687.	3.9	6